



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE7244SL		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005346831						
<b>Package</b>		PG-SSOP-24-7		<b>Weight*</b>		147.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.128	3.49	3.49	34854	34854
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8464	
wire	non noble metal	copper	7440-50-8	50.568	34.37	35.27	343683	352676
	noble metal	gold	7440-57-5	0.765	0.52	0.52	5196	5196
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1160
plastics	plastics	epoxy resin	-	7.854	5.34		53380	
	inorganic material	silicondioxide	60676-86-0	77.347	52.55	58.01	525681	580221
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11417	11417
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2482	2482
glue	plastics	acrylic resin	-	0.426	0.29		2894	
	noble metal	silver	7440-22-4	1.510	1.03	1.32	10260	13154
*deviation	< 10%				Sum in total:		100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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